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GooLED-LUM-6850 Pin Fin Heat Sink Φ68mm for LumiLEDs

Mounting Options and Drawings & Dimensions

3

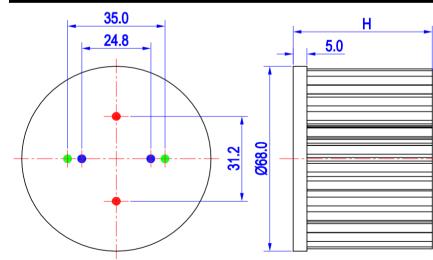
Example:GooLED-LUM-6850-B-1,2 Example:GooLED-LUM-68 Height (mm) Anodising Color B-Black C-Clear

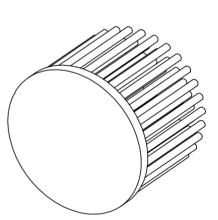
Z-Custom

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

Mounting Option	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Stella Series	Olivia series	INKEAD	DEPTH	DISTANCE
1	LUXEON 1204HD; LUXEON 1205HD;	/	/	FN14637-S; FN14828-M;	M3	6.5mm	24.8mm/ 2-@180°
2		/			M3	6.5mm	31.2mm/ 2-@180°
	LUXEON 1204; LUXEON 1205;	BJB Holder 47.319.2011.50			МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	LUXEON 1208;	TE Holder 2213130-1					
	LUXEON 1204HD; LUXEON 1205HD;	TE Holder 2213382-1		1			
	LUXEON L04; LUXEON L05; LUXEON L08;	BJB Holder 47.319.2131.50					
		TE Holder 2213401-1					





Ex.order code - 12

Mounting Options - see graphics for

means option 1 and 2 combined

details Combinations available

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GooLED-LUM-6850 Pin Fin Heat Sink Ø68mm for LumiLEDs

The product deta table

GooLED	Model No.	GooLED-LUM-6850		
GOOLED	Heatsink Size	Ф68хH50mm		
	Heatsink Material	AL1070		
	Finish	Black Anodized		
	Weight (g)	153.0		
	Dissipated power (Ths-amb,50°C)	15.5 (W)		
	Cooling surface area (mm ²)	59562		
	Thermal Resistance (Rhs-amb)	3.23 (°C/W)		

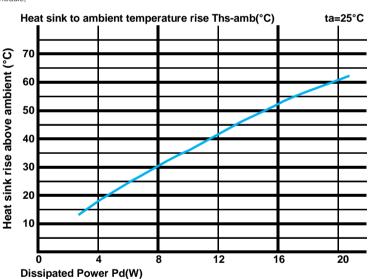
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: $Pd = Pe \times (1 - \eta L)$.

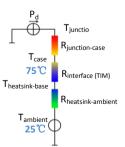
Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		GooLED-LUM-6850	
Dissipated Power Pd(W)	4.0	4.25	17.0
	8.0	3.75	30.0
	12.0	3.42	41.0
	16.0	3.25	52.0
	20.0	3.00	60.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta)/Pd$

heta - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{\text{interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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